

# PRESSPACK IGBT

A modern design employing state-of-the-art technologies



## Designed primarily for grid applications - high current, high voltage, high reliability

- Novel housing solution using a typical hermetically-sealed hockey puck ceramic housing with internal compliance mechanism ensures optimum contact pressure distribution across all chips with standard thyristor heatsink and clamp assemblies and prevents over-pressurisation of chips
- Chip assemblies employ silver sintering technology for improved robustness and improved thermal characteristics
- New chipset designed and manufactured by Dynex in UK
- First product will be 4.5kV with 125mm contact diameter rated from 1100A (1:1 IGBT:FRD ratio) to 3000A (all-IGBT)

## Dynex Presspack IGBT Range

Diameter (mm)	1:1 Ratio	2:1 Ratio	All - IGBT
125 mm	1.1kA	1.5kA	2.1kA
	1.5kA	2kA	3kA
150mm	2kA	3kA	4kA+